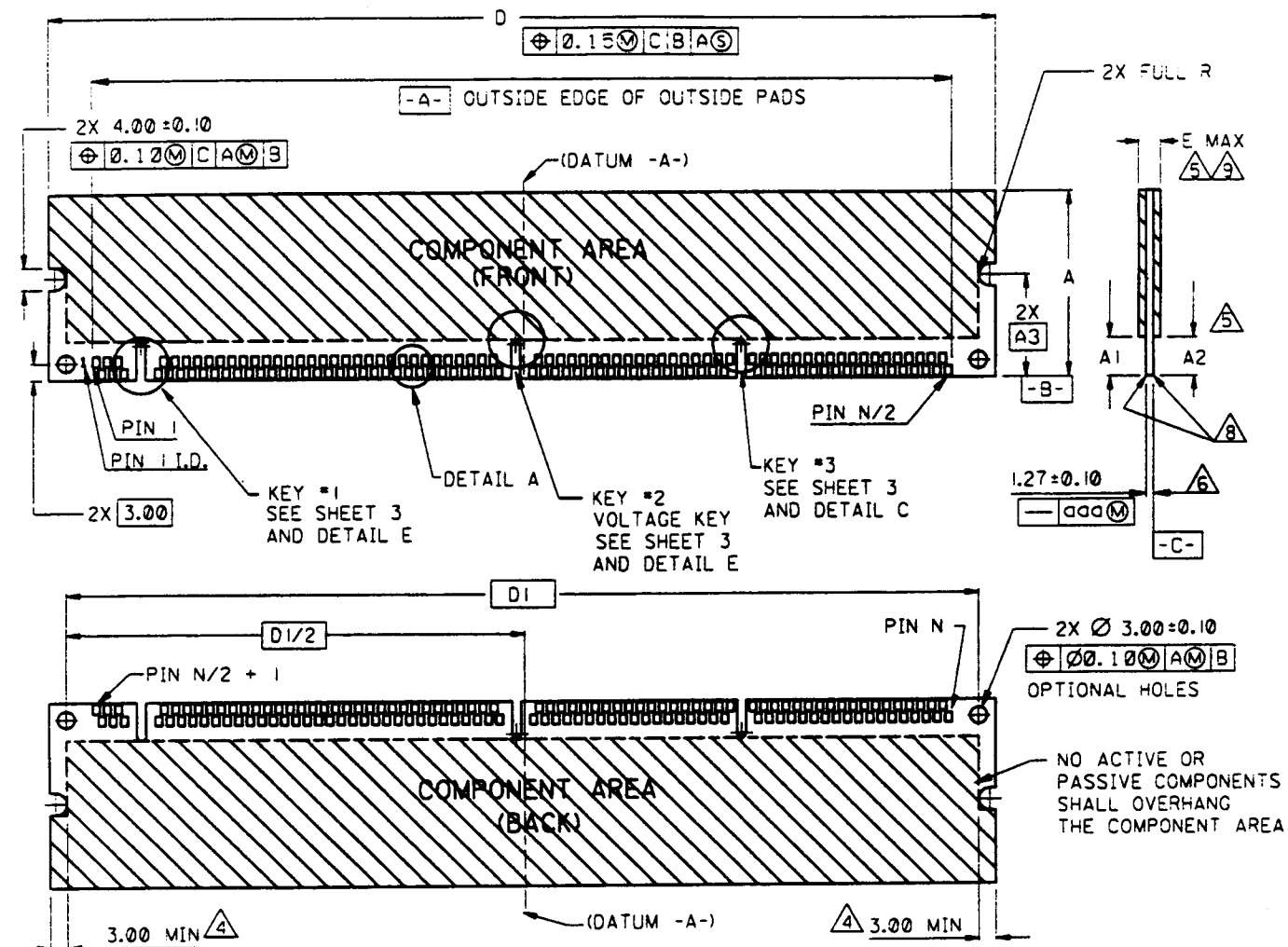


PRINCIPAL DATUMS & DIMENSIONS



JEDEC
SOLID STATE PRODUCT
OUTLINE

THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC
JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE
IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.

TITLE

DUAL INLINE MEMORY
MODULE (DIMM) FAMILY
1.00 LEAD CENTERS

JESD-30 DESIGNATOR

ISSUE

A

DATE

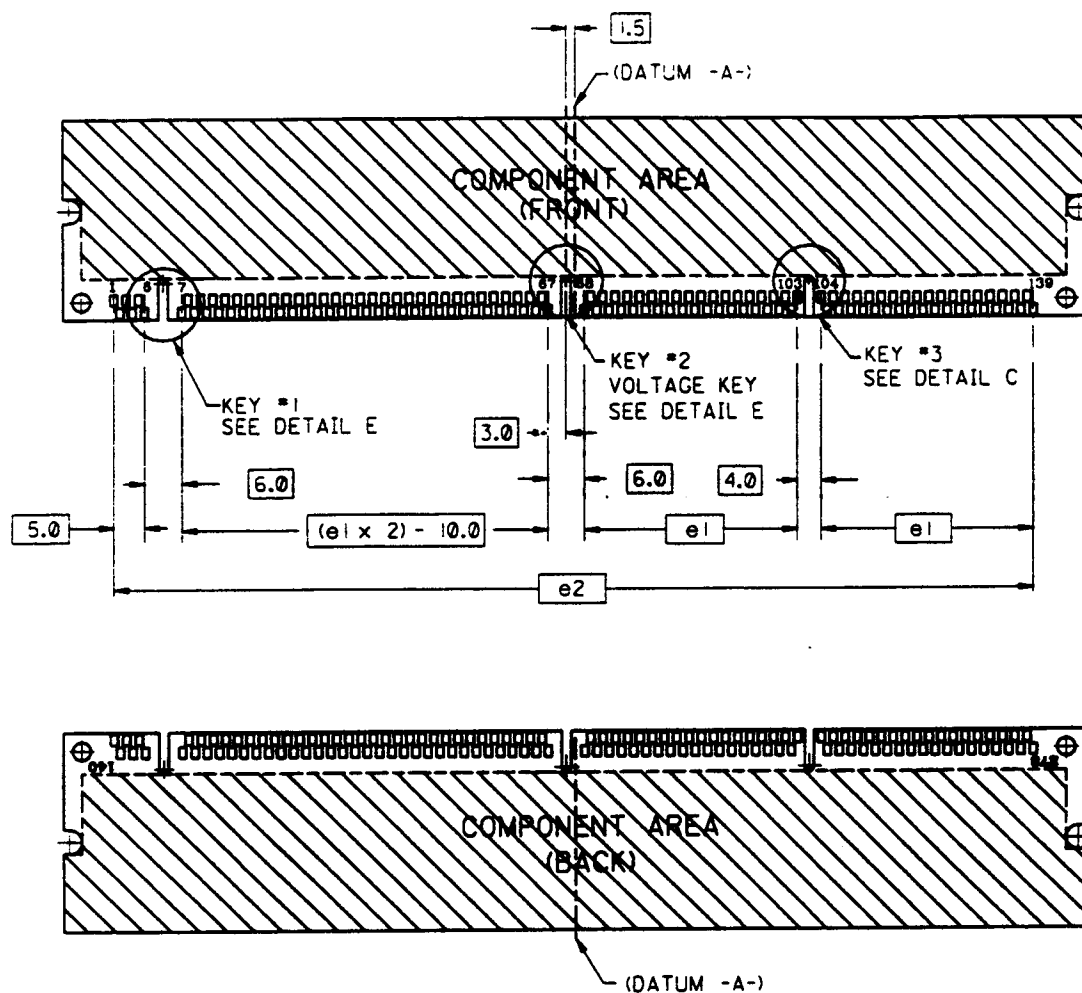
OCT
1995

MO-179

SHEET


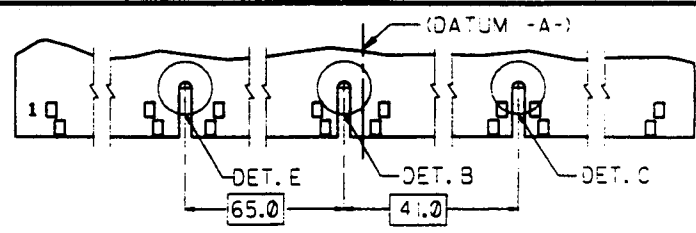
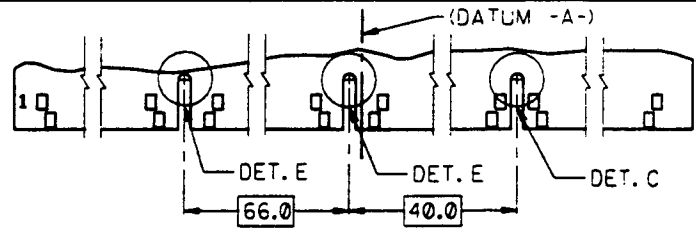
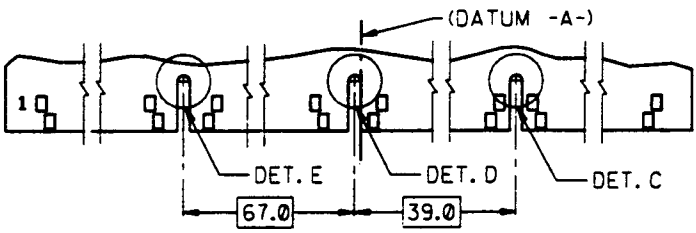
1 OF 6

CONFIGURATION #1



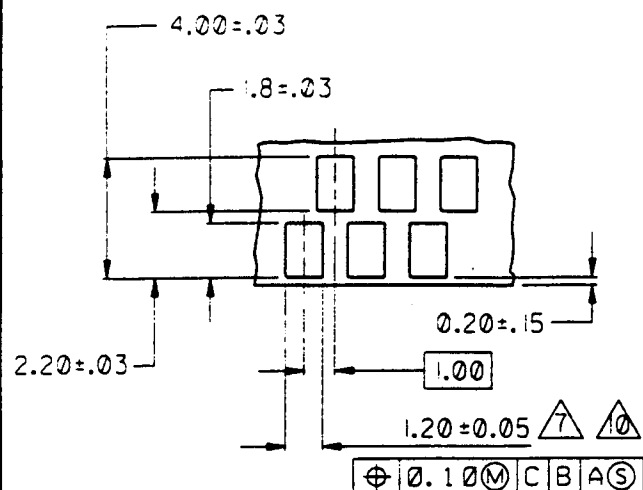
<p>JEDEC SOLID STATE PRODUCT OUTLINE</p>	<p>TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 1.00 LEAD CENTERS</p>	<p>ISSUE A</p>	<p>DATE OCT 1995</p>	<p>M0-179</p>	<p>SHEET 2 OF 6</p>
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CONFIGURATION

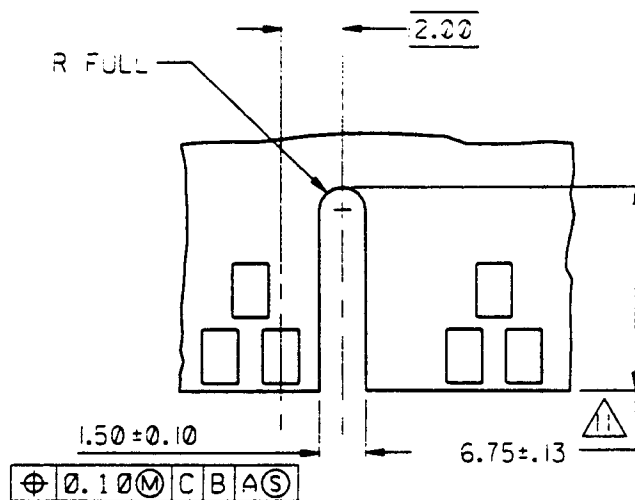
ITEM NO. 	KEY #1	KEY #2 VOLTAGE KEY	KEY #3	NO. PINS	MODULE KEY POSITION DETAIL
D1	CONF.*1	X.XV	CONF.*1	278	
D2	CONF.*1	3.3V	CONF.*1	278	
D3	CONF.*1	X.XV	CONF.*1	278	

NOTE: REFER TO SHEET 4 FOR DETAILS.

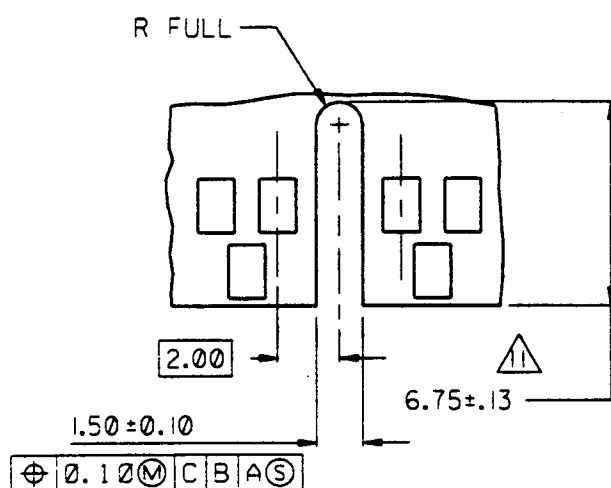
JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 1.00 LEAD CENTERS	ISSUE A	DATE OCT 1995	MO-179	SHEET 3 OF 6
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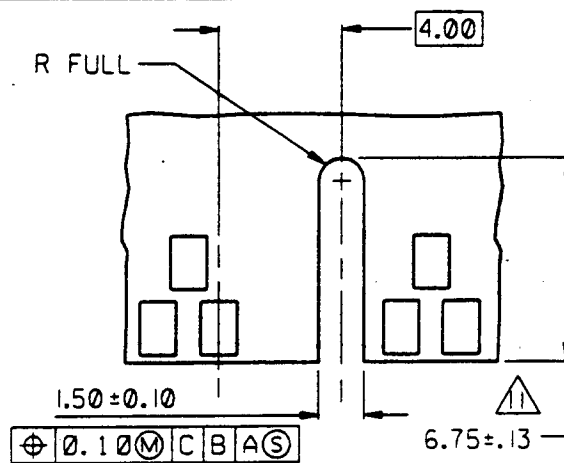
DETAIL A
(CONTACT PAD DETAIL)



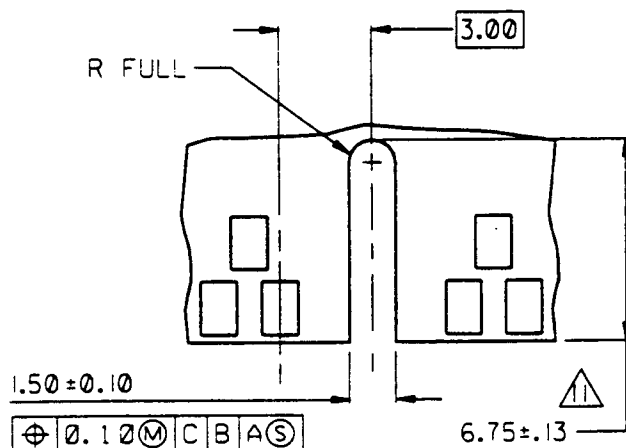
DETAIL B
KEY #1 OR #2
LEFT OFFSET KEYWAY



DETAIL C
KEY #3



DETAIL D
KEY #1 OR #2
RIGHT OFFSET KEYWAY



DETAIL E
KEY #1 OR #2
CENTERED KEYWAY

Notes:

- 1 DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2 TOLERANCES ON ALL DIMENSIONS $\pm .13$ UNLESS OTHERWISE SPECIFIED.
- 3 ALL DIMENSIONS ARE IN MILLIMETERS



4 3.00 mm MIN. APPLIES TO BOTH 4.00 mm WIDE NOTCH LENGTH AND COMPONENT KEEPOUT AREA.



5 DIMENSION APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDES.



6 CARD THICKNESS APPLIES ACROSS CONTACT TABS AND INCLUDES PLATING AND/OR METALIZATION. STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY A1, A2 AND D1.



7 N IS THE TOTAL NUMBER OF CIRCUITS CONTACTS (PIN, LEADS, TABS, OR PADS).



8 LEADING EDGE OF CONTACT PAD SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.



9 WHEN SOJ DEVICES ARE USED FOR ASSEMBLY OF THIS MODULE. THE MAX THICKNESS OVERALL SHALL NOT EXCEED 9.00 mm. WHEN TSOP DEVICES ARE USED THE MAX THICKNESS OVERALL SHALL NOT EXCEED 4.00 mm.



10 APPLICATION NOTE:
RECOMMENDED PLATING FOR GOLD CONTACT PAD: GOLD PLATING
0.75 MICROMETER MIN OVER Ni PLATING 2.0 MICROMETER MIN.



11 KEYWAY MAY ENCROACH COMPONENT ZONE (.03 MAX.).

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 1.00 LEAD CENTERS	ISSUE A	DATE OCT 1995	MO-179	SHEET 5 OF 6
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SYMBOL	VARIATIONS NOMINAL HEIGHT 33.00							
	AA-VI				AB-VI			
	MIN	NOM	MAX	NOTE	MIN	NOM	MAX	NOTE
A	32.87	33.00	33.13		32.87	33.00	33.13	
A1	6.85				6.85			
A2	6.85			5	6.85			5
A3	17.80 BSC				17.80 BSC			
D	167.47	167.60	167.73		167.47	167.60	167.73	
D1	161.47	161.60	161.73		161.47	161.60	161.73	
e1	35.00 BSC				35.00 BSC			
e2	151.00 BSC				151.00 BSC			
E			4.00	5,9			9.00	5,9
aaa			0.40				0.40	
N	278			7	278			7
NOTE	1, 2, 3				1, 2, 3			
REF	14-021				14-021			
ISSUE	A				A			

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE DUAL INLINE MEMORY MODULE (DIMM) FAMILY 1.00 LEAD CENTERS	ISSUE A	DATE OCT 1995	MO-179	SHEET 6 OF 6
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